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With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

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Contact us

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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China









RGTV60TK65D

650V 30A Field Stop Trench IGBT

V _{CES}	650V
I _{C (100°C)}	20A
V _{CE(sat) (Typ.)}	1.5V@I _C =30A
P_D	76W

Features

- 1) Low Collector Emitter Saturation Voltage
- 2) High Speed Switching & Low Switching Loss
- 3) Short Circuit Withstand Time 2µs
- 4) Built in Very Fast & Soft Recovery FRD
- 4) Pb free Lead Plating; RoHS Compliant

Applications

Solar Inverter

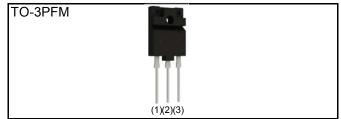
UPS

Welding

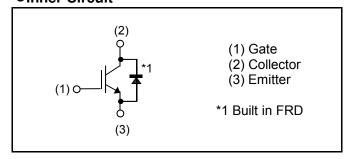
ΙH

PFC

Outline



●Inner Circuit



Packaging Specifications

	Packaging	Tube
	Reel Size (mm)	-
Typo	Tape Width (mm)	-
Туре	Basic Ordering Unit (pcs)	450
	Packing Code	C11
	Marking	RGTV60TK65D

● Absolute Maximum Ratings (at T_C = 25°C unless otherwise specified)

Parameter		Symbol	Value	Unit	
Collector - Emitter Voltage		V _{CES}	650	V	
Gate - Emitter Voltage		V_{GES}	±30	V	
Collector Current	T _C = 25°C	I _C	33	А	
Collector Current	T _C = 100°C	I _C	20	А	
Pulsed Collector Current		I _{CP} *1	120	А	
Diode Forward Current	T _C = 25°C	I _F	34	А	
Diode Forward Current	T _C = 100°C	I _F	19	А	
Diode Pulsed Forward Current		I _{FP} *1	120	А	
$T_C = 25^{\circ}C$		P_{D}	76	W	
Power Dissipation	T _C = 100°C	P_{D}	38	W	
Operating Junction Temperature		T _j	-40 to +175	°C	
Storage Temperature		T _{stg}	-55 to +175	°C	

^{*1} Pulse width limited by T_{imax}.

●Thermal Resistance

Parameter	Cumbal	Values			Unit
Farameter	Symbol	Min.	Тур.	Max.	Offic
Thermal Resistance IGBT Junction - Case	$R_{\theta(j-c)}$	ı	ı	1.97	°C/W
Thermal Resistance Diode Junction - Case	$R_{\theta(j-c)}$	1	1	2.29	C/VV

●IGBT Electrical Characteristics (at T_j = 25°C unless otherwise specified)

Parameter	Symbol	Conditions	Values			Unit	
r ai ainietei	Syllibol	Conditions	Min.	Тур.	Max.	Offic	
Collector - Emitter Breakdown Voltage	BV _{CES}	$I_{C} = 10 \mu A, V_{GE} = 0 V$	650	-	-	V	
Collector Cut - off Current	I _{CES}	V _{CE} = 650V, V _{GE} = 0V	-	-	10	μΑ	
Gate - Emitter Leakage Current	I _{GES}	$V_{GE} = \pm 30V, V_{CE} = 0V$	-	-	±200	nA	
Gate - Emitter Threshold Voltage	$V_{\text{GE(th)}}$	$V_{CE} = 5V, I_{C} = 21.0 \text{mA}$	5.0	6.0	7.0	V	
Collector - Emitter Saturation Voltage	V _{CE(sat)}	$I_C = 30A$, $V_{GE} = 15V$ $T_j = 25$ °C $T_j = 175$ °C	-	1.5 1.85	1.9 -	V	

●IGBT Electrical Characteristics (at T_j = 25°C unless otherwise specified)

Davamatar	Cymphol	Conditions		Unit		
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Input Capacitance	C _{ies}	V _{CE} = 30V	-	1730	-	
Output Capacitance	C _{oes}	V _{GE} = 0V	-	74	-	pF
Reverse Transfer Capacitance	C _{res}	f = 1MHz	-	30	-	
Total Gate Charge	Q_g	V _{CE} = 400V	-	64	-	
Gate - Emitter Charge	Q_{ge}	I _C = 30A	-	14	-	nC
Gate - Collector Charge	Q_{gc}	V _{GE} = 15V	-	24	-	
Turn - on Delay Time	t _{d(on)}	$I_C = 30A, V_{CC} = 400V$	-	33	-	
Rise Time	t _r	$V_{GE} = 15V, R_{G} = 10\Omega$	-	12	-	20
Turn - off Delay Time	$t_{d(off)}$	T _j = 25°C	-	105	-	ns
Fall Time	t _f	Inductive Load	-	40	-	
Turn - on Switching Loss	E _{on}	*E _{on} includes diode	-	0.57	-	
Turn - off Switching Loss	E _{off}	reverse recovery	-	0.50	-	mJ
Turn - on Delay Time	t _{d(on)}	I _C = 30A, V _{CC} = 400V	-	32	-	
Rise Time	t _r	$V_{GE} = 15V, R_{G} = 10\Omega$	-	13	-	20
Turn - off Delay Time	t _{d(off)}	T _j = 175°C	-	121	-	ns
Fall Time	t _f	Inductive Load	-	80	-	
Turn - on Switching Loss	E _{on}	*E _{on} includes diode	-	0.63	-	
Turn - off Switching Loss	E _{off}	reverse recovery	-	0.72	-	mJ
		I _C = 120A, V _{CC} = 520V				
Reverse Bias Safe Operating Area	RBSOA	$V_P = 650V, V_{GE} = 15V$	FU	LL SQUA	ARE	-
		$R_G = 100\Omega, T_j = 175^{\circ}C$				
		$V_{CC} \le 360V$				
Short Circuit Withstand Time	t _{sc}	V _{GE} = 15V	2	-	-	μs
		T _j = 25°C				

●FRD Electrical Characteristics (at T_j = 25°C unless otherwise specified)

Parameter	Symbol	Conditions	Values			Unit	
Parameter	Syllibol	Conditions	Min.	Тур.	Max.	Ullit	
Diode Forward Voltage	V_{F}	$I_F = 30A$ $T_j = 25^{\circ}C$ $T_j = 175^{\circ}C$	-	1.45 1.55	1.9 -	V	
Diode Reverse Recovery Time	t _{rr}		-	95	-	ns	
Diode Peak Reverse Recovery Current	I _{rr}	$I_F = 30A$ $V_{CC} = 400V$ $di_F/dt = 200A/\mu s$ $T_j = 25^{\circ}C$	-	8.1	-	А	
Diode Reverse Recovery Charge	Q_{rr}		-	0.42	-	μC	
Diode Reverse Recovery Energy	E _{rr}		-	19.3	-	μJ	
Diode Reverse Recovery Time	t _{rr}	$I_F = 30A$ $V_{CC} = 400V$ $di_F/dt = 200A/\mu s$ $T_j = 175^{\circ}C$	-	155	-	ns	
Diode Peak Reverse Recovery Current	I _{rr}		1	10.4	1	А	
Diode Reverse Recovery Charge	Q_{rr}		-	0.95	-	μC	
Diode Reverse Recovery Energy	E _{rr}		-	62.5	-	μJ	

Fig.1 Power Dissipation vs. Case Temperature

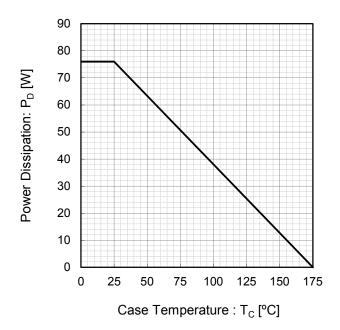


Fig.2 Collector Current vs. Case Temperature

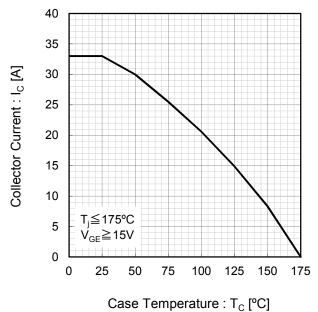


Fig.3 Forward Bias Safe Operating Area

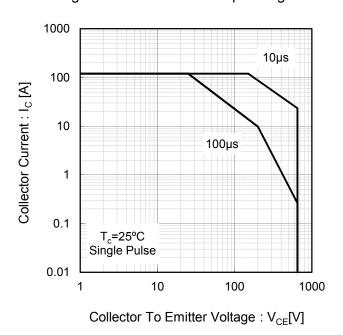


Fig.4 Reverse Bias Safe Operating Area

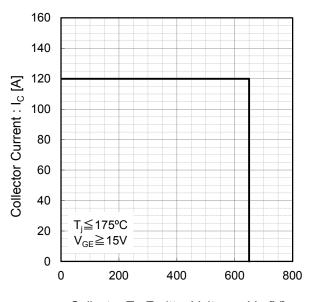


Fig.5 Typical Output Characteristics

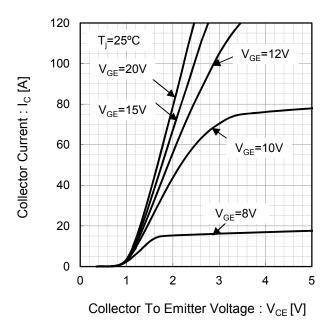
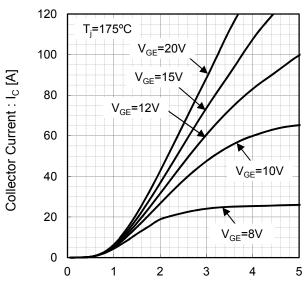


Fig.6 Typical Output Characteristics



Collector To Emitter Voltage : V_{CE} [V]

Fig.7 Typical Transfer Characteristics

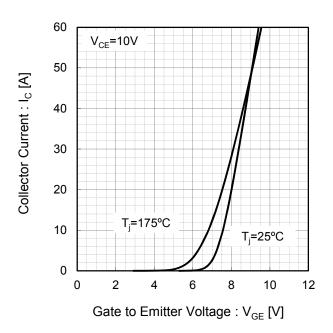


Fig.8 Typical Collector To Emitter Saturation Voltage vs. Junction Temperature

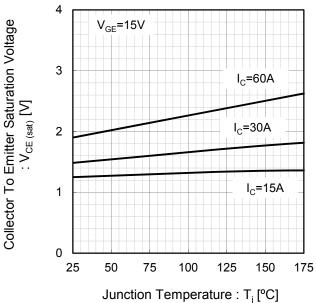
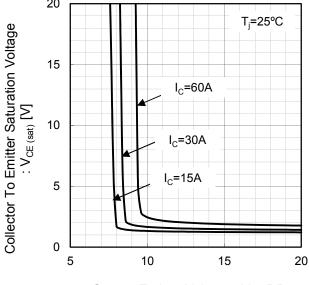
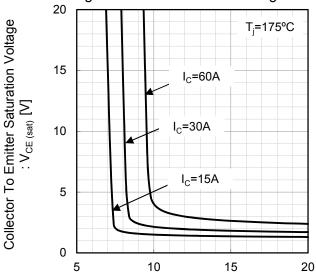


Fig.9 Typical Collector To Emitter Saturation Voltage vs. Gate To Emitter Voltage



Gate to Emitter Voltage : $V_{GE}[V]$

Fig.10 Typical Collector To Emitter Saturation Voltage vs. Gate To Emitter Voltage



Gate to Emitter Voltage : V_{GE} [V]

Fig.11 Typical Switching Time vs. Collector Current

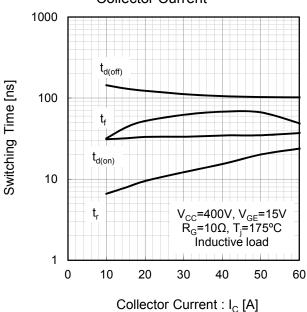
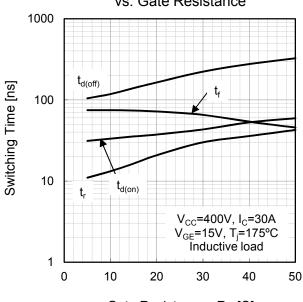


Fig.12 Typical Switching Time vs. Gate Resistance



Switching Energy Losses [mJ]

0.1

0.01

0

10

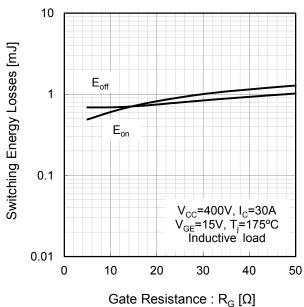
20

• Electrical Characteristic Curves

Collector Current 10 1 E_{off}

Fig.13 Typical Switching Energy Losses vs.

Fig.14 Typical Switching Energy Losses vs. **Gate Resistance**



30 Collector Current : I_C [A]

 V_{CC} =400V, V_{GE} =15V R_{G} =10 Ω , T_{j} =175°C Inductive load

40

50

60

Fig.15 Typical Capacitance vs. Collector To Emitter Voltage 10000 Cies 1000 Capacitance [pF] Coes 100 Cres 10 f=1MHz V_{GE}=0V T_i=25°C 0.01 0.1 1 10 100

Collector To Emitter Voltage : $V_{CE}[V]$

Fig.16 Typical Gate Charge

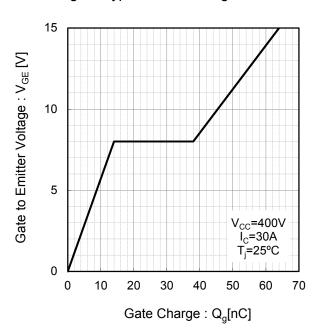


Fig.17 Typical Diode Forward Current vs. Forward Voltage 120 100 Forward Current : I_F [A] 80 60 40 T_i=25°C 20 T_i=175°C 0 0.5 1.5 2 2.5 3 0 1

Forward Voltage : V_F[V]

Fig.18 Typical Diode Reverse Recovery Time vs. Forward Current 400 Reverse Recovery Time : t_{rr} [ns] 300 200 T_i=175°C 100 V_{CC} =400V di_F/dt=200A/µs T_i=25°C Inductive load 0 0 10 20 30 40 50 60 Forward Current : I_F [A]

Fig.19 Typical Diode Reverse Recovery Current vs. Forward Current 20 Reverse Recovery Curren : I_{rr}[A] 15 T_i=175°C 10 5 T_i=25°C V_{CC}=400V di_F/dt=200A/μs Inductive load 0 10 20 30 40 50 60 Forward Current : I_F [A]

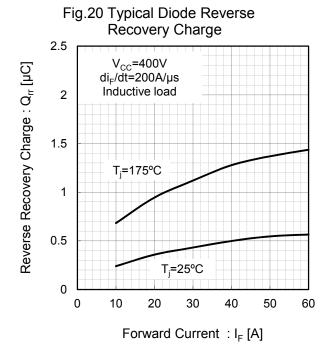


Fig.21 Typical IGBT Transient Thermal Impedance

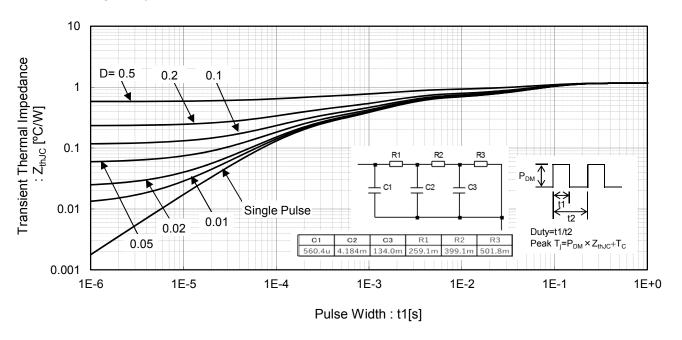
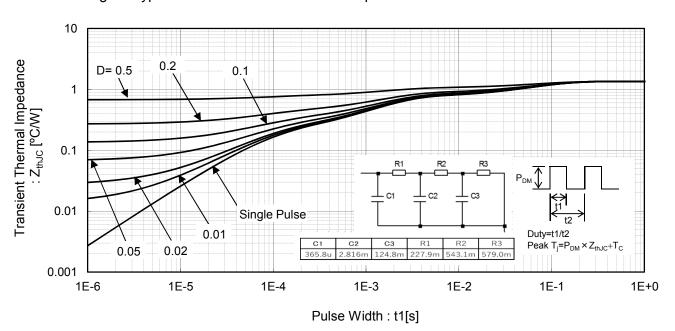


Fig.22 Typical Diode Transient Thermal Impedance



•Inductive Load Switching Circuit and Waveform

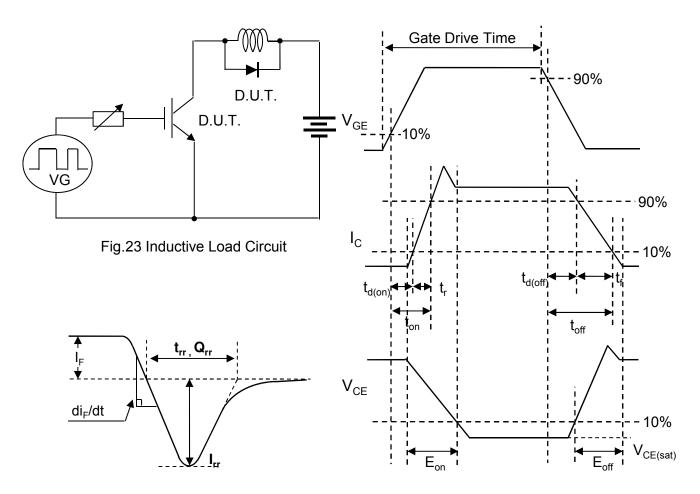


Fig.25 Diode Reverce Recovery Waveform

Fig.24 Inductive Load Waveform

Notes

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RGTV60TK65D - Web Page

Part Number	RGTV60TK65D
Package	TO-3PFM
Unit Quantity	450
Minimum Package Quantity	30
Packing Type	Tube
Constitution Materials List	inquiry
RoHS	Yes